



Material Content Data Sheet



Sales Product Name				TLE4942-1C		Issued		9. January 2019	
MA#				MA000862102					
Package				PG-SSO-2-4		Weight*		167.45 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.458	1.47	1.47	14680	14680	
leadframe	non noble metal	chromium	7440-47-3	0.288	0.17		1720		
	non noble metal	titanium	7440-32-6	0.288	0.17		1720		
	non noble metal	nickel	7440-02-0	0.384	0.23		2293		
	non noble metal	tin	7440-31-5	0.576	0.34		3439		
	non noble metal	copper	7440-50-8	94.449	56.42	57.33	564033	573205	
wire	noble metal	gold	7440-57-5	0.041	0.02	0.02	246	246	
encapsulation	organic material	carbon black	1333-86-4	0.459	0.27		2742		
	plastics	brominated resin	-	0.574	0.34		3428		
	inorganic material	antimonytrioxide	1309-64-4	1.148	0.69		6855		
	plastics	epoxy resin	-	10.446	6.24		62382		
	inorganic material	silicondioxide	60676-86-0	44.769	26.74	34.28	267353	342760	
leadfinish	non noble metal	tin	7440-31-5	6.247	3.73	3.73	37305	37305	
plating	noble metal	silver	7440-22-4	0.986	0.59	0.59	5886	5886	
glue	plastics	epoxy resin	-	0.155	0.09		928		
	noble metal	silver	7440-22-4	0.621	0.37	0.46	3710	4638	
smd	inorganic material	leadoxide	1317-36-8	0.001	0.00		4		
	inorganic material	leadtitanate	12060-00-3	0.018	0.01		106		
	inorganic material	titandioxide	13463-67-7	0.085	0.05		509		
	inorganic material	bismuth trioxide	1304-76-3	0.147	0.09		877		
	noble metal	palladium	7440-05-3	0.273	0.16		1630		
	noble metal	silver	7440-22-4	0.858	0.51		5126		
	inorganic material	bariumtitanate	12047-27-7	2.182	1.30	2.12	13028	21280	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7 (c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

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